

## EUROPEAN PATENT OFFICE

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TITLE : PATTERN FORMATION BY THICK FILM  
PASTE



**ABSTRACT :** PURPOSE: To form patterns with openings as small as about 100 micrometers by firstly providing resist patterns on a multi-layer thick film base for LSI's to correspond to the openings, then applying a thick film Insulating paste to the thus treated base and finally removing the resists to form the desired patterns.

**CONSTITUTION:** A photosensitive polymeric material 2 having a predetermined thickness is put in contact with a base 1. The photosensitive polymeric material 2 is exposed to light through a prescribed photomask, followed by development with a developing solution, to leave parts of the material 2 corresponding to openings as resists 3. Then an insulating paste 4 is applied over the base 1 in a thickness such that the resists are all covered. Thereupon, the resists 3 are removed together with the paste 4 just overlying each resist. The remaining portions of the paste 4 are dried and burnt to form patterns with openings 5 on the base 1.

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